Apogee® Mechanical Debonder

With DataStream™ Technology

Eliminate process variability and manual debonding risks with a semi-automated system designed for repeatability, substrate safety, and operational efficiency. Supports a wide range of adhesives, wafer sizes, and process scales.

Cost Effective Equipment

Serving the Semiconductor Industry Since 1987

BENEFITS

- NRTL listed for OSHA and ANSI compliance
- Compact and self contained
- Fully automated debond sequence
- Semi-automated wafer loading/unloading
- Device wafer debonding on film frame to fully support device wafer and minimize handling risk
- Enhanced logging with DataStream™ technology

SPECIFICATIONS

- Substrate sizes: 50 mm to 200 mm
- Room temperature
- Peel force: 1 to 75 N
- Force resolution: 1 N

RELIABILITY

- Industry leading uptime
- 1-year full warranty on parts and labor
- Complimentary remote technical support for the life of the product
- Application process assistance for the life of the product

PROGRAMMABILITY

- Full-color touchscreen graphical user interface (GUI)
- Recipe control of temperatures, force, speed, and time
- Unlimited user-defined program steps for each recipe
- 0.1-second resolution for step times (time:0-9,999.9 s/step)
- Up/download DataStream™ process parameters via native USB and Ethernet ports
- Process logging and traceability for every wafer
- On-line graphical process charts
- Remote process management

Total Throughput	Up to 20 WPH
Qualified Wafer Materials	SiC, GaN, GaAs, InP, sapphire, silicon, glass, and more...
System Uptime	>98% over a 12-month period
Mean Time To Repair (MTTR)	< 24 hours
Mean Time Between Failures (MTBF; hours, cycles)	>600 hours, 6,000 cycles

UTILITIES

- Voltage Ranges: 110-125, 208-230VAC Single Phase
- Power Requirements: 950 W, 9.5 A (max)
- Vacuum: 1/4" Push to Connect, <20" Hg (33kPa)
- N2/CDA: 1/4" Push to Connect, 70psi (482kPa)

DIMENSIONS

- 24" (610mm) W x 33.5" (851mm) D x 73.25" (1861mm) H
- Machine Weight 337 lb (152.9 kg) *excluding accessories*

DATASTREAM™ TECHNOLOGY: CONNECTING THE SEMICONDUCTOR INDUSTRY

DataStream™ technology gives you access to all of your connected Apogee® manufacturing equipment in one place to track, access, and modify your systems via a web browser. This technology provides manufacturers with the ability to process and visualize data in real time and search and export that data into a number of different formats.

Real-Time Process Information

- Constant feedback of process information for monitoring critical process parameters
- Streamlined interface between different process modules
- Visual cues on process status & health

Environmental Monitoring

- Monitoring of temperature & humidity allows for stricter control of critical processes
- Set preconditions and tolerances for monitored parameters
- On-screen, colored visual cues for deviation from controlled specs

Advanced Recipe Creation

- Seamless switching between basic and advanced recipe creation methods
- Plain-English recipe translation
- Predefined process commands
- Unlimited process steps
- Unlimited recipe storage

Data Logging & Export

- Export data logs into commonly readable formats for further analysis and process troubleshooting
- Increase process efficiency
- Identify process control deviations
- Analyze multiple processes for best known method (BKM) development